

产品规格书

Specification of products

产品名称: 整流管模块

产品型号: MDK55A-M1

浙江世菱半导体有限公司
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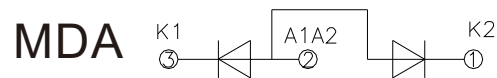
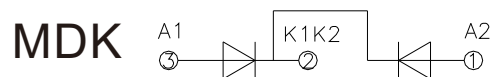
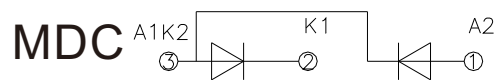
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拟制	审核	核准
林益龙	曹剑龙	宗瑞

SYMBOL	CHARACTERISTIC	TEST CONDI TIONS	T _j (°C)	VALUE			UNIT
				Min	Type	Max	
I _{F(AV)}	Mean forward current	180° half sine wave 50Hz Single side cooled, T _C =100°C	150		55		A
I _{F(RMS)}	RMS forward current	Single side cooled, T _C =100°C	150		86		A
V _{RRM}	Repetitive peak reverse voltage	V _{RRM} tp=10ms V _{RSM} = V _{DRM} &V _{RRM} +200V	150	600		1800	V
I _{RRM}	Repetitive peak current	at V _{RRM}	150			5	mA
I _{FSM}	Surge forward current	10ms half sine wave	150			1.15	KA
I ² t	I ² T for fusing coordination	V _R =0.6V _{RRM}					6.6
V _{FO}	Threshold voltage		150			0.52	V
r _F	Forward slop resistance						1.70
V _{FM}	Peak forward voltage	I _{FM} =160A	25		1.3		V
R _{th(j-c)}	Thermal resistance Junction to heatsink	At 180° sine Single side cooled				0.59	°C /W
V _{iso}	Isolation voltage	50Hz, RM. S, t=1min, I _{iso} : 1mA (max)		3000			V
F _m	Terminal connection torque(M5)				4.0		N.m
	Mounting torque(M6)				5.0		N.m
T _{stg}	Stored temperature			-40		125	°C
W _t	Weight				100		g
Outline							

OUTLINE DRAWING & CIRCUIT DIAGRAM



Rating and Characteristic

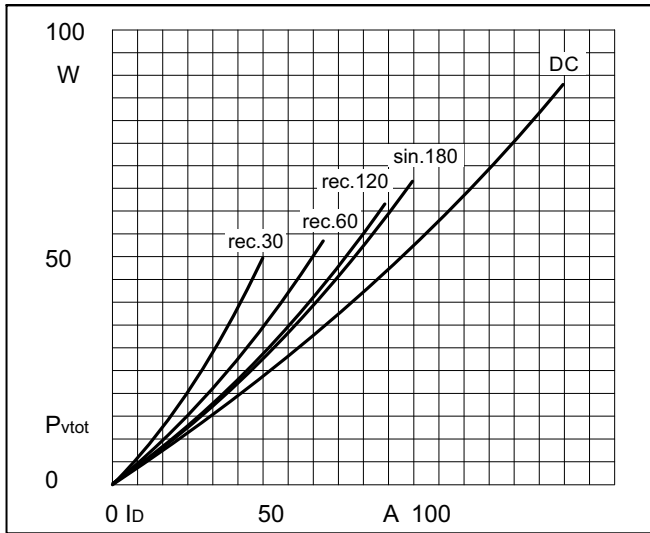


Fig1. Power dissipation

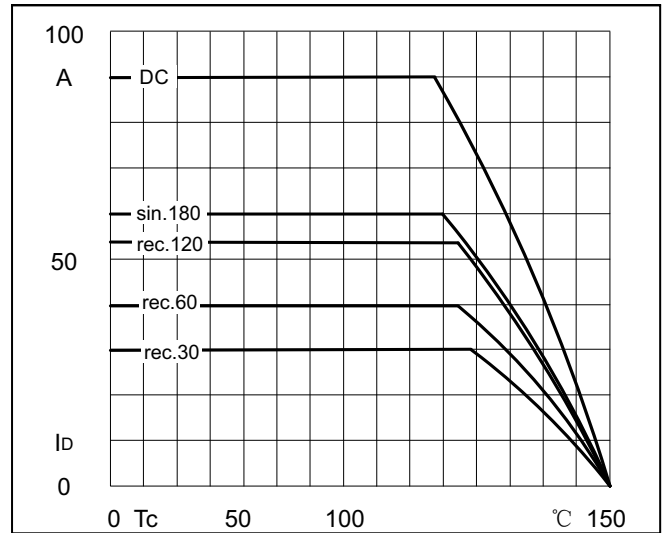


Fig2. Forward Current Derating Curve

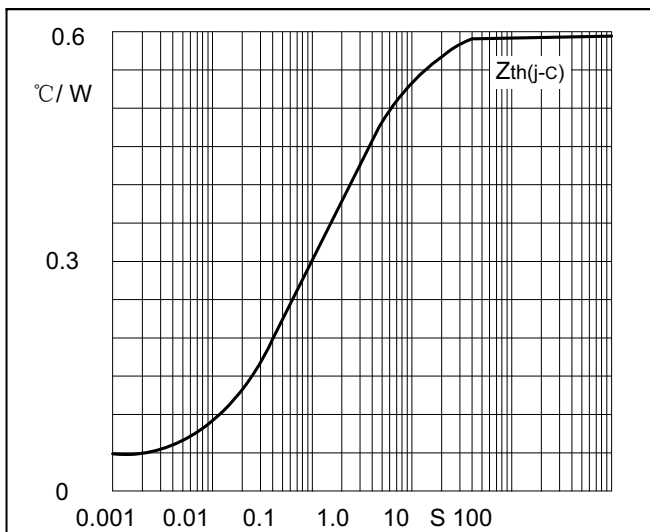


Fig3. Transient thermal impedance

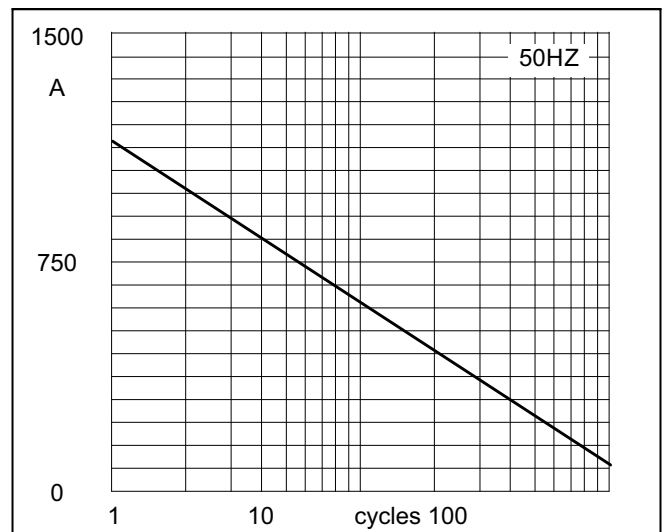


Fig4. Max Non-Repetitive Forward Surge Current

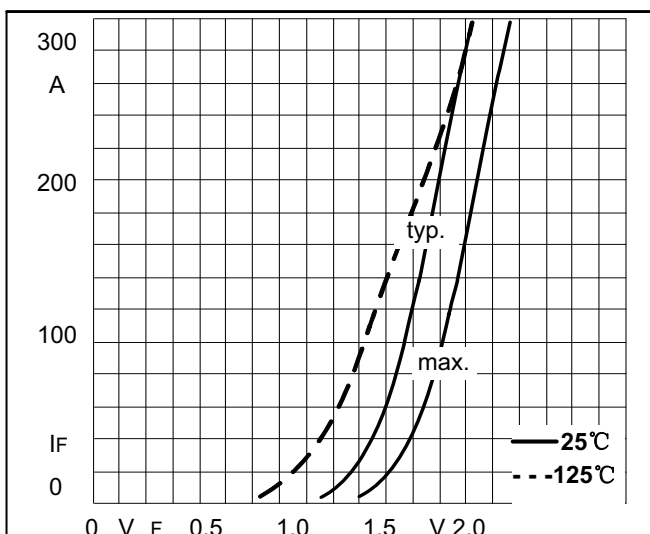


Fig5. Forward Characteristics

Outside Dimension

